

11. Sequential Circuits

1. Realization of Registers (Latches, Flip-Flops)

1. Dynamic Registers
2. Static Registers

2. Pipeline

3. Clock distribution – Clock networks

4. Clock generation

The role of the Clock- Network

Most widely spread network

Extremely high Fan-Out

Highest switching frequency

Significant share of power loss

Signal propagation in the clock network must be very fast

Signal propagation in the clock network must be very uniform (Skew!)

Summary of Delay

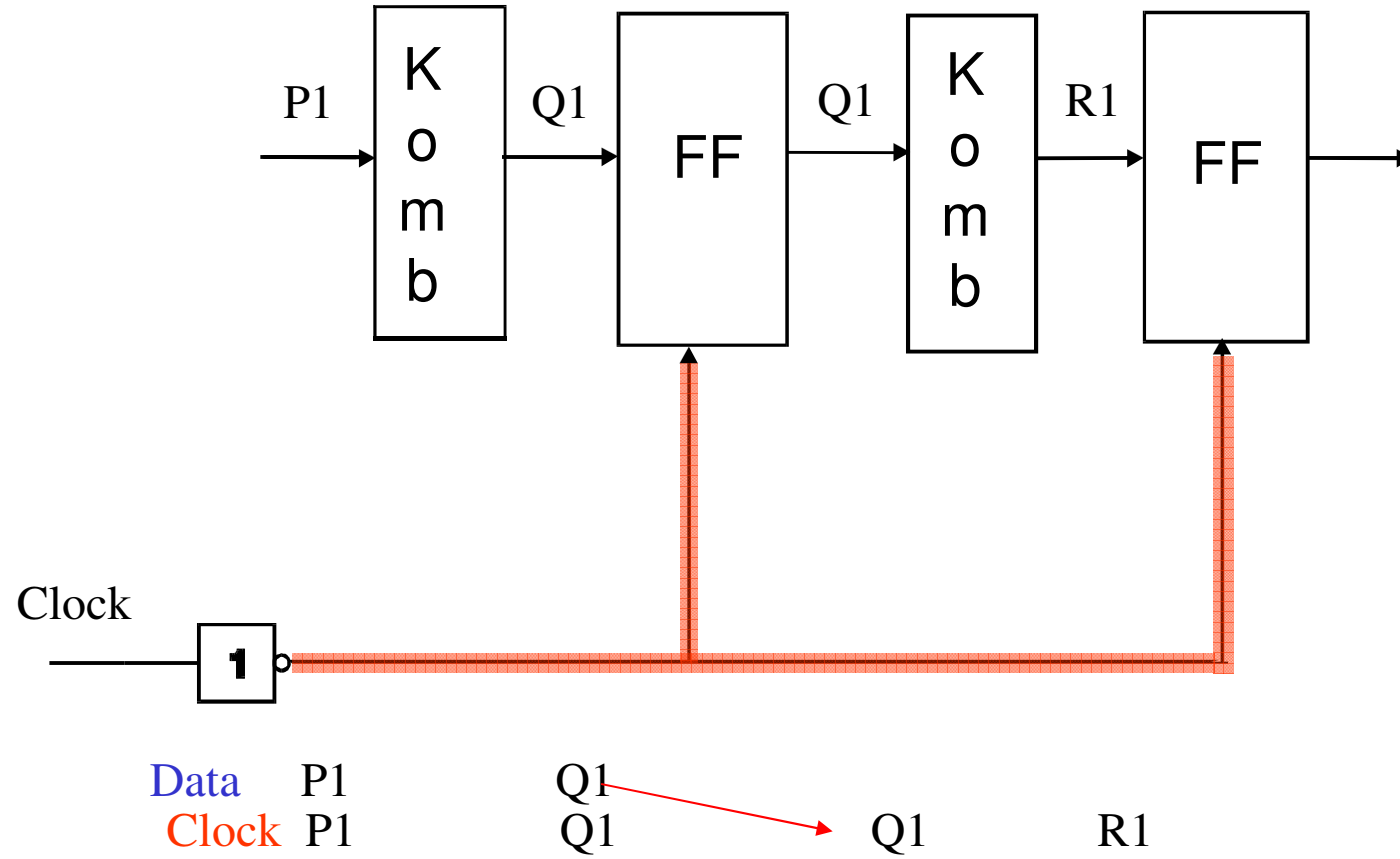
Gate Delay

- Delay through a logic element
- independent of routing
- relatively predictable

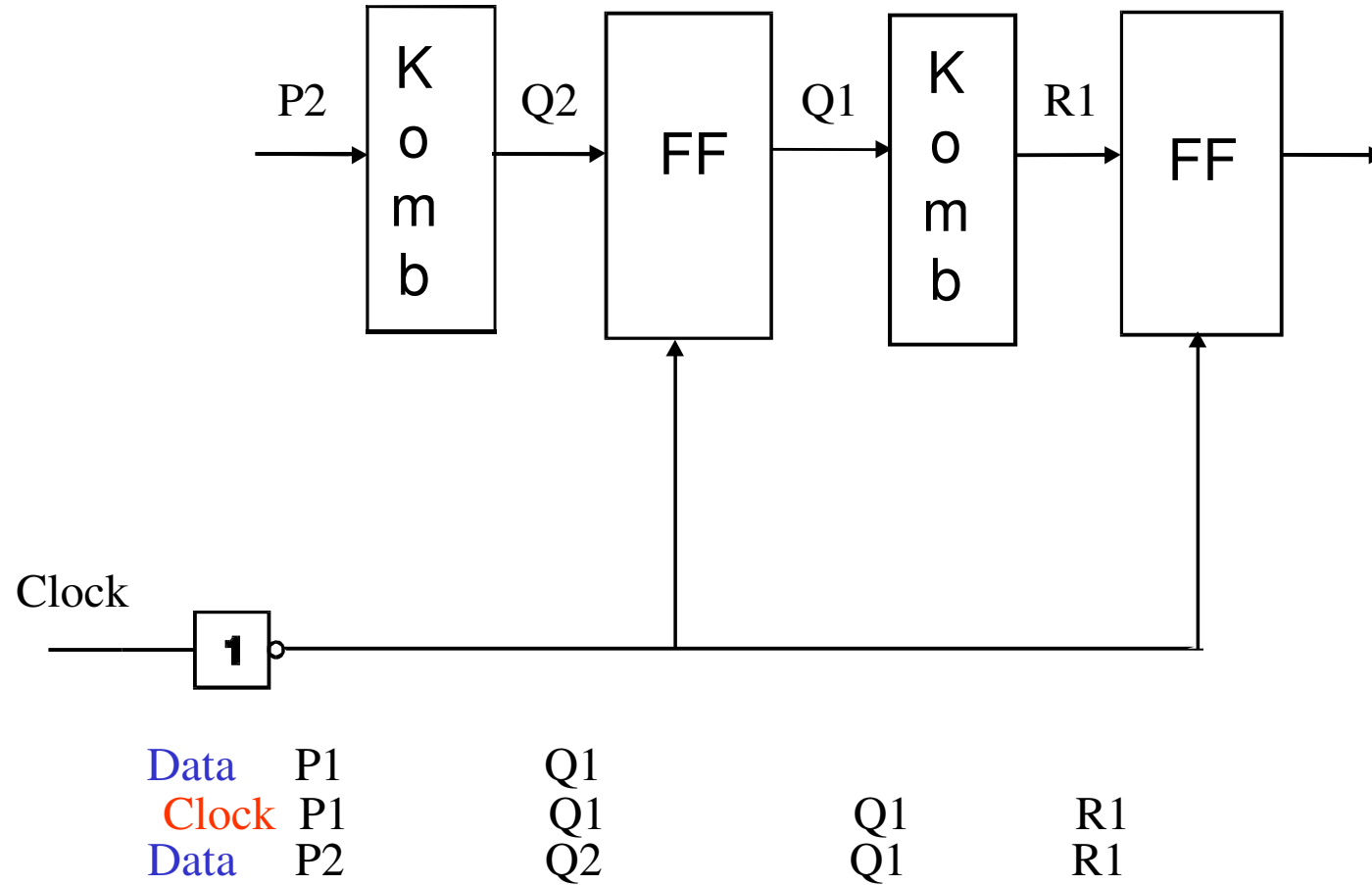
Interconnect Delay

- Signal delay through the wires
- strongly depending on routing
- difficult to predict

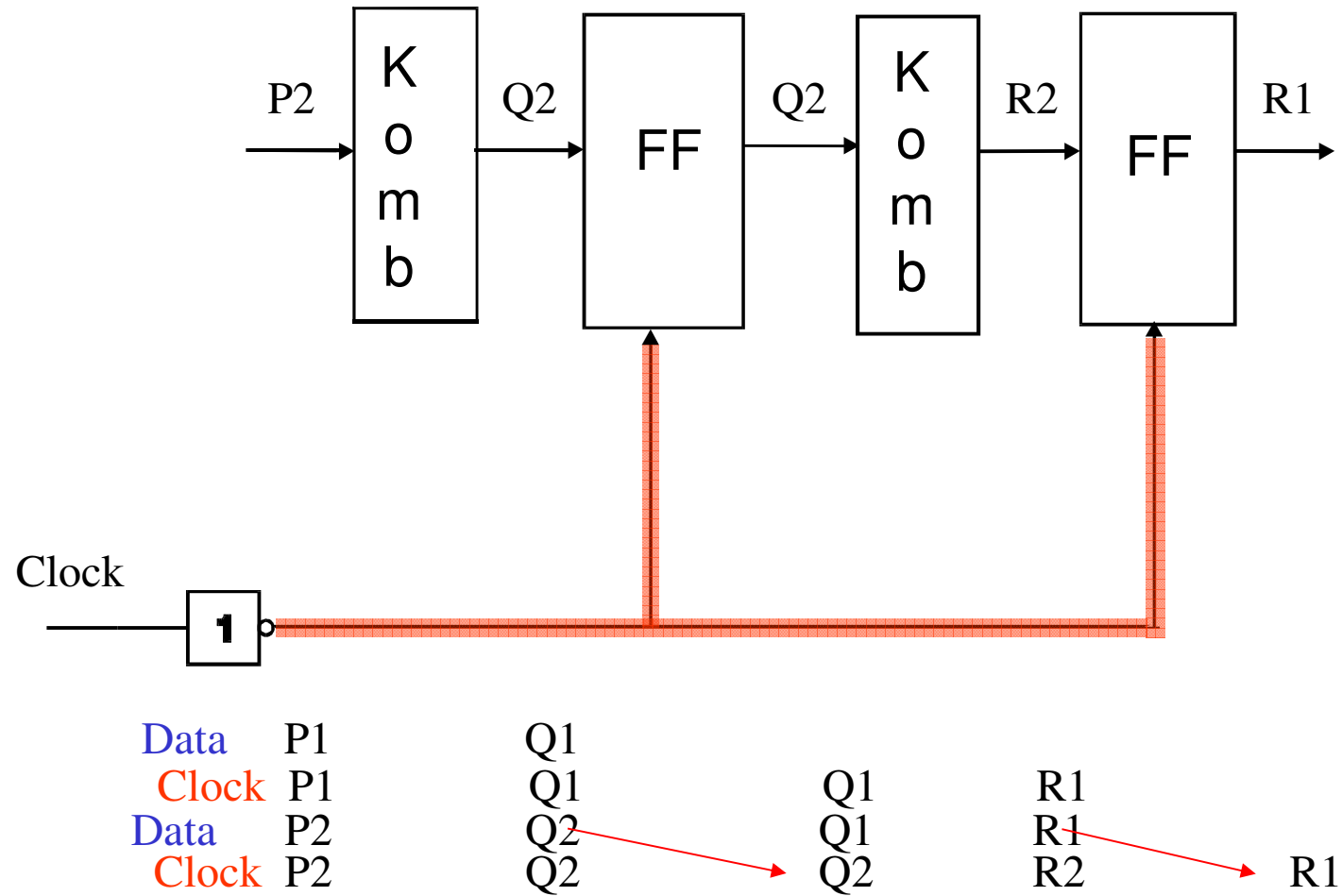
Clock- / Driver



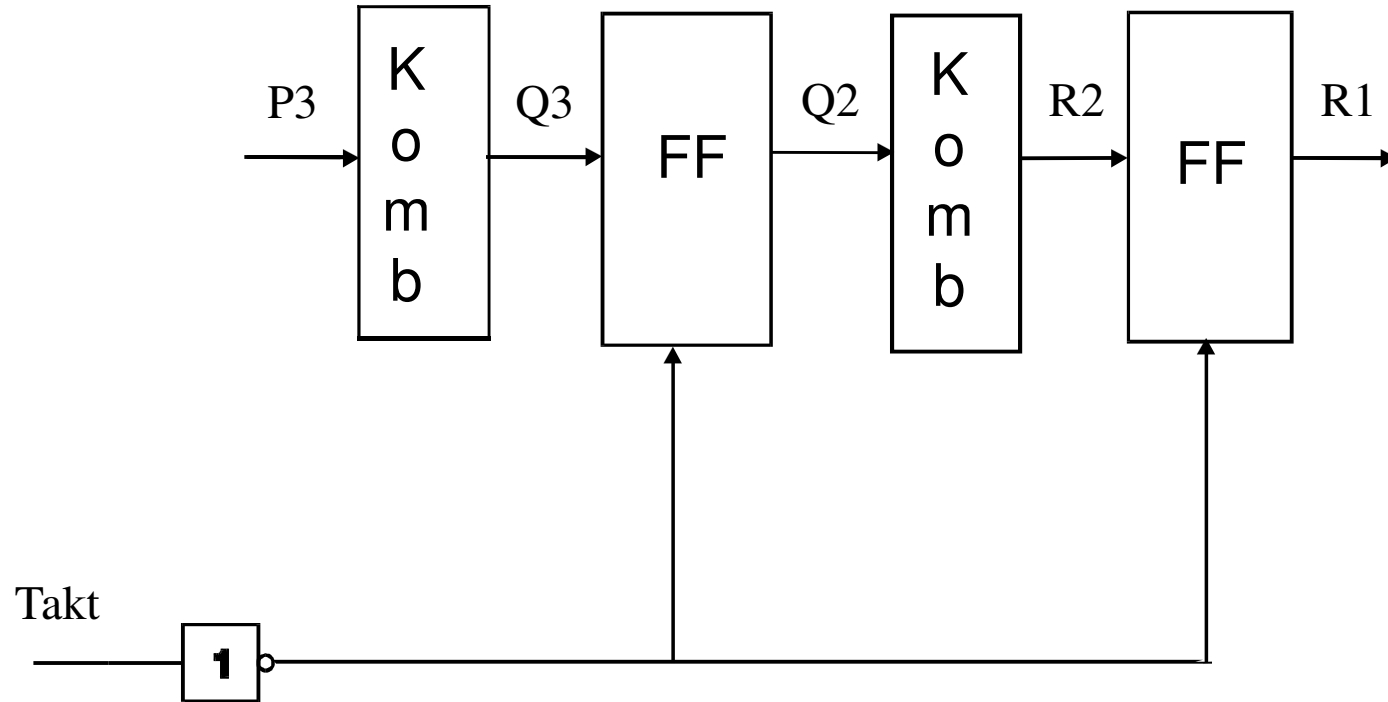
Clock- / Driver



Clock- / Driver

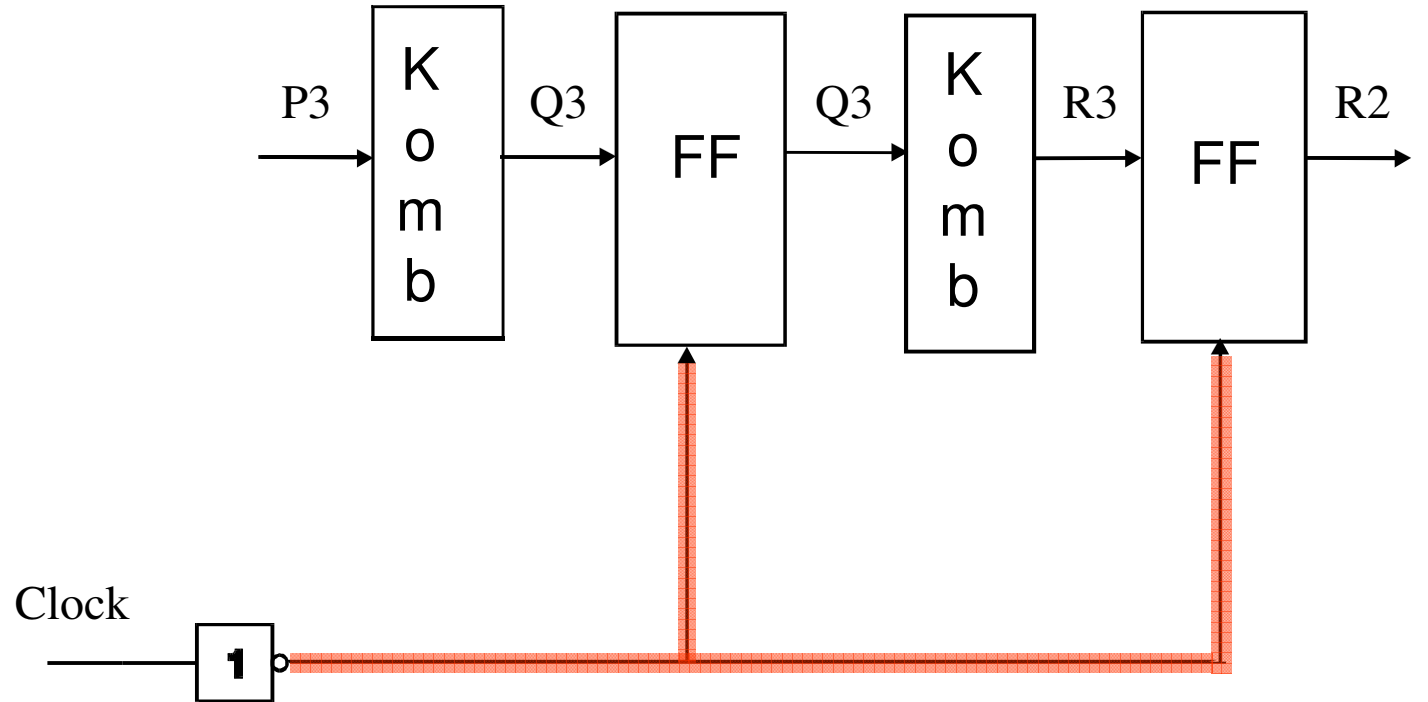


Clock- / Driver



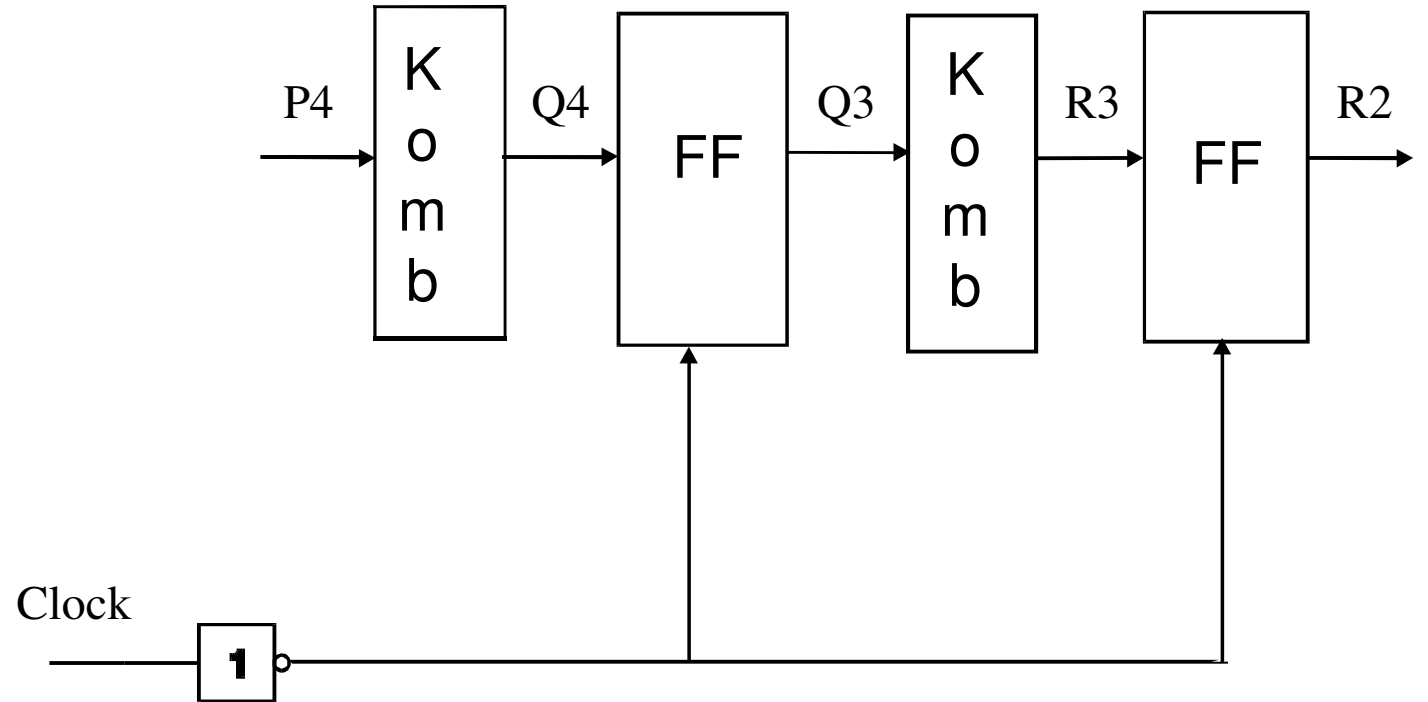
Data	P1	Q1			
Clock	P1	Q1	Q1	R1	
Data	P2	Q2	Q1	R1	
Clock	P2	Q2	Q2	R2	R1
Data	P3	Q3	Q2	R2	R1

Clock- / Driver



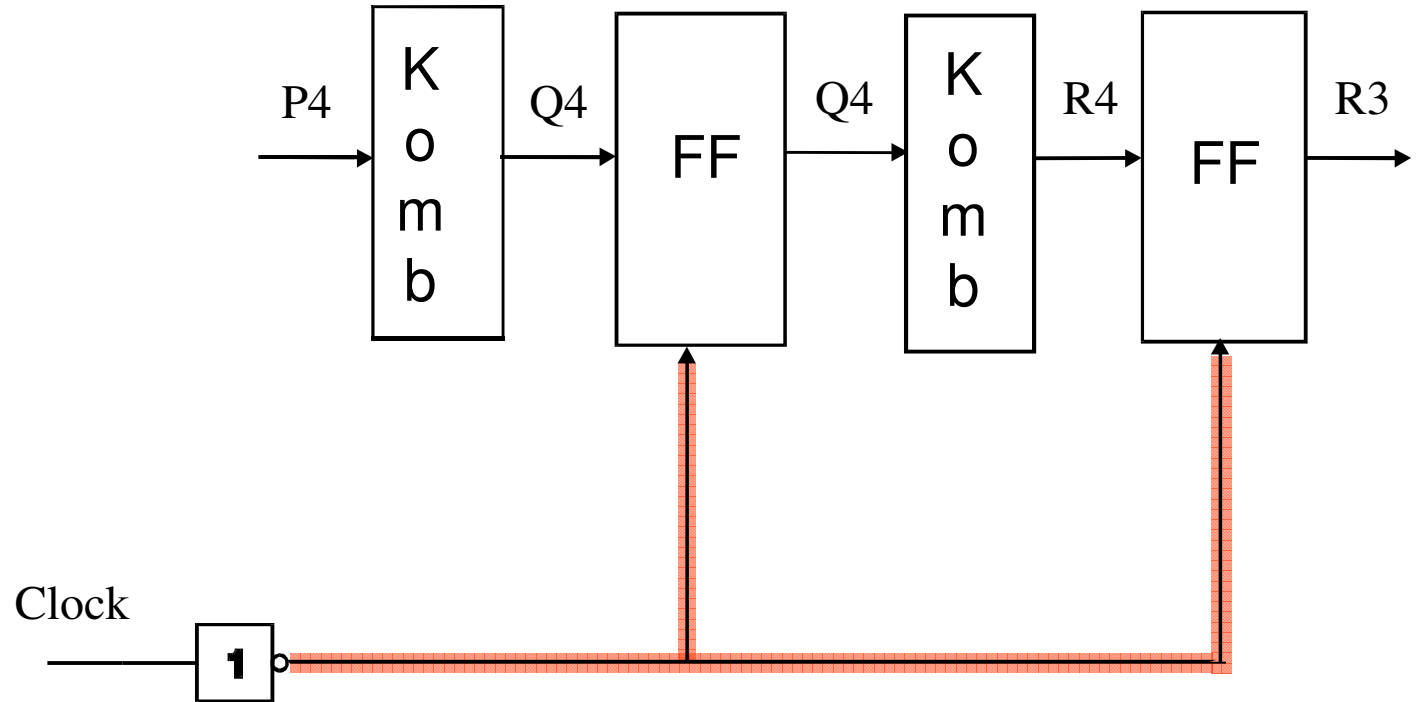
Data	P1	Q1			
Clock	P1	Q1	Q1	R1	
Data	P2	Q2	Q1	R1	
Clock	P2	Q2	Q2	R2	R1
Data	P3	Q3	Q2	R2	R1
Clock	P3	Q3	Q3	R3	R2

Clock- / Driver



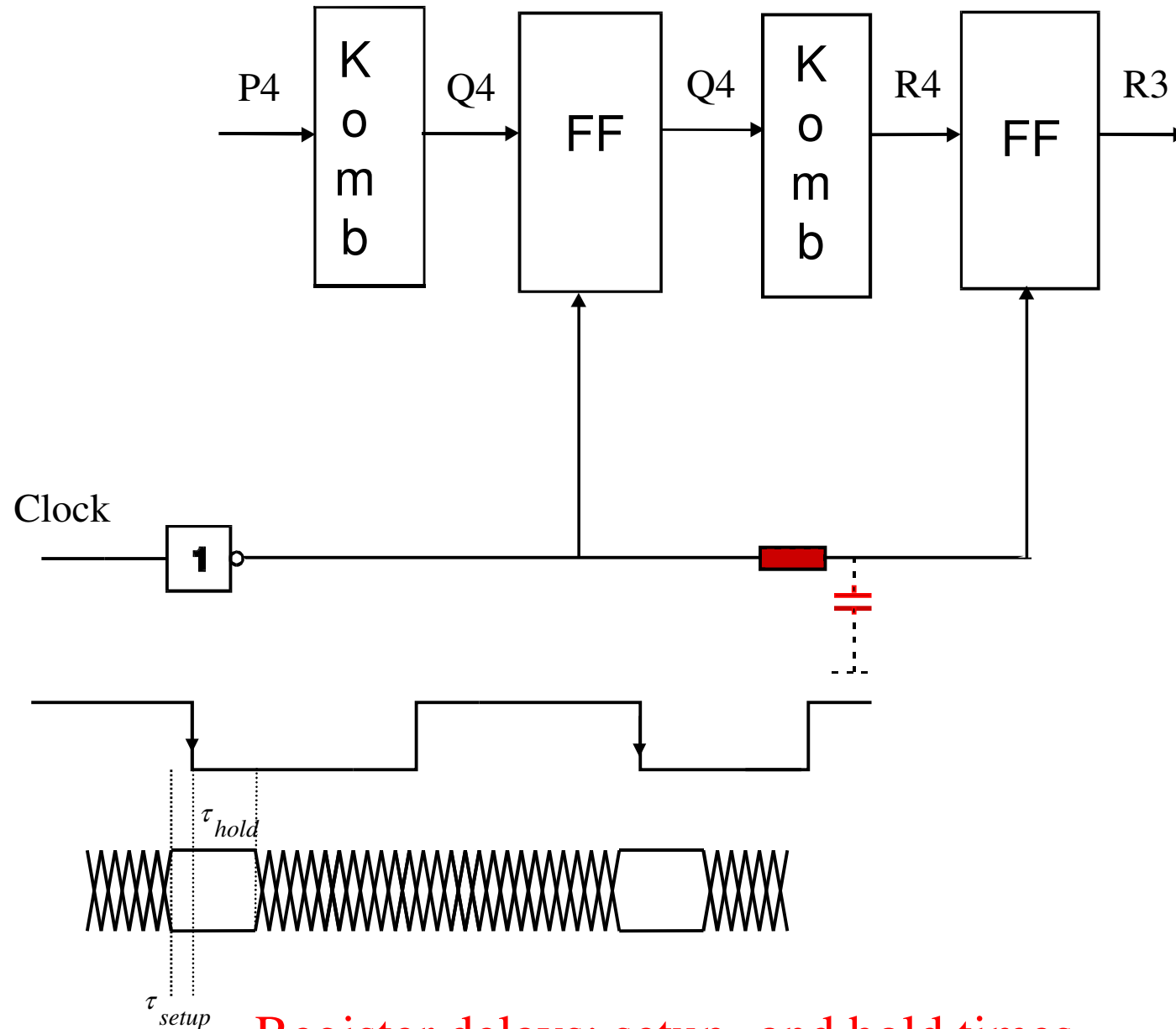
Data	P1	Q1			
Clock	P1	Q1	Q1	R1	
Data	P2	Q2	Q1	R1	
Clock	P2	Q2	Q2	R2	R1
Data	P3	Q3	Q2	R2	R1
Clock	P3	Q3	Q3	R3	R2
Data	P4	Q4	Q3	R3	R2

Clock- / Driver



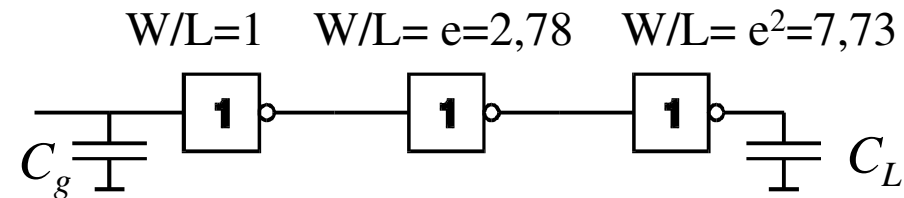
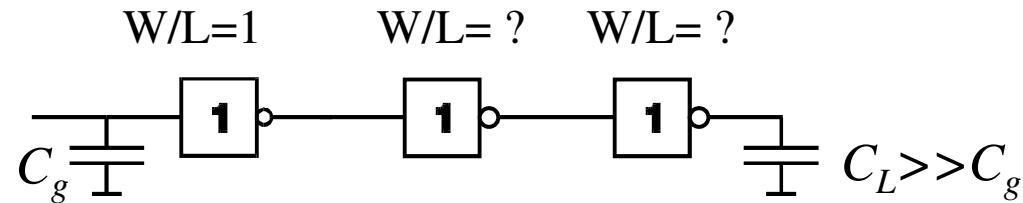
	P1	Q1			
Clock	P1	Q1		R1	
Data	P2	Q2	Q1	R1	
Clock	P2	Q2	Q2	R2	R1
Data	P3	Q3	Q2	R2	R1
Clock	P3	Q3	Q3	R3	R2
Data	P4	Q4	Q3	R3	R2
Clock	P4	Q4	Q4	R4	R3

Clock- / Driver

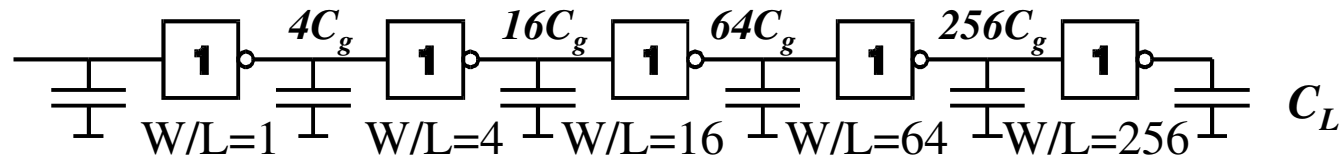


Register delays: setup- and hold times

Chain of drivers as clock driver

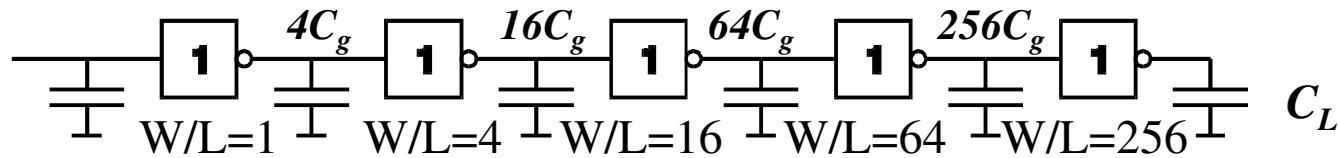


$$\text{number of stages} = \text{Log}_n \left(\frac{C_L}{C_g} \right)$$

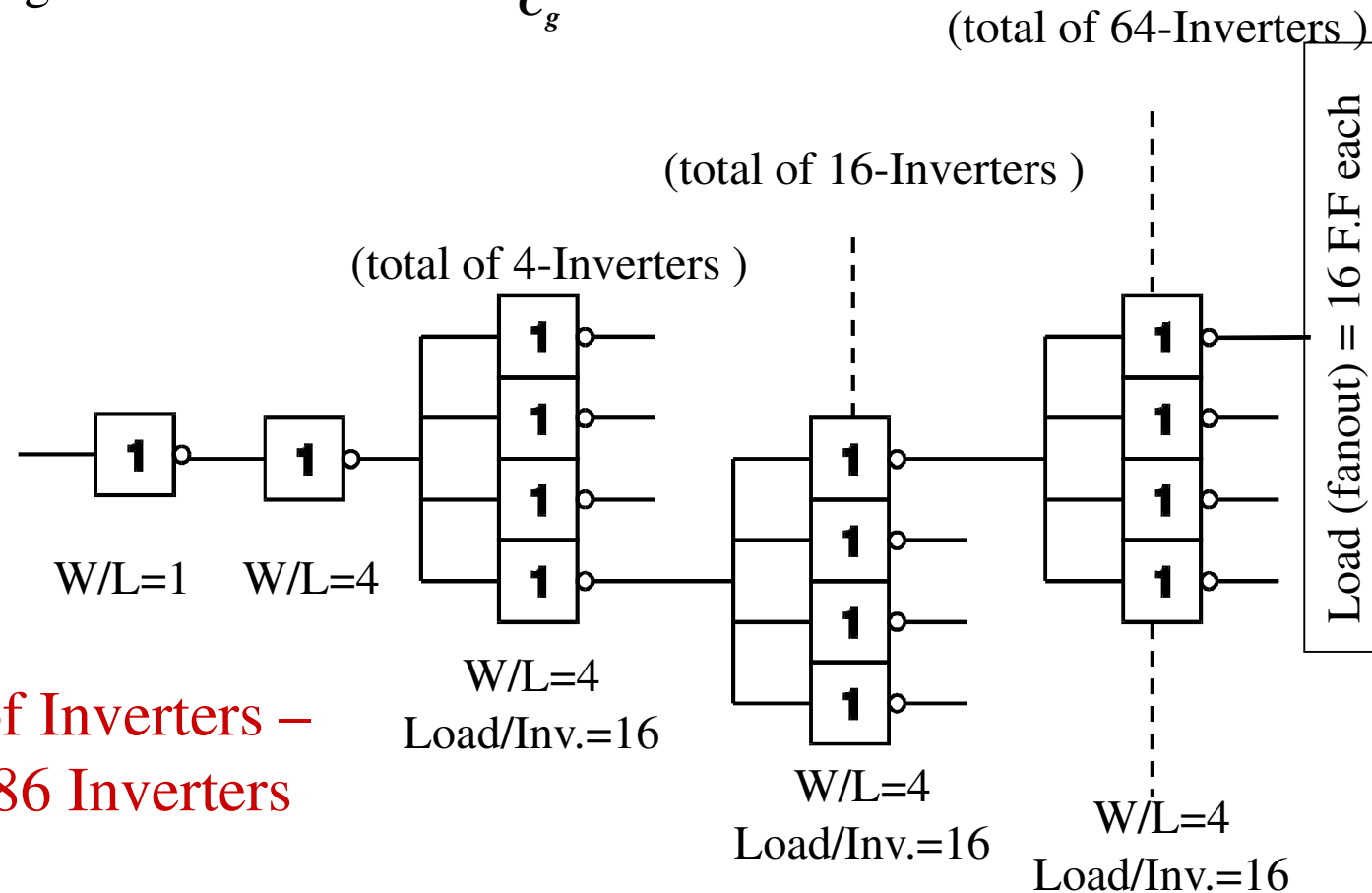


Five stage chain of drivers for $\frac{C_L}{C_g} = 1024$ eg. 1024 Latches
or 512 Flip-Flops

Driver arrangement for clock sub-network

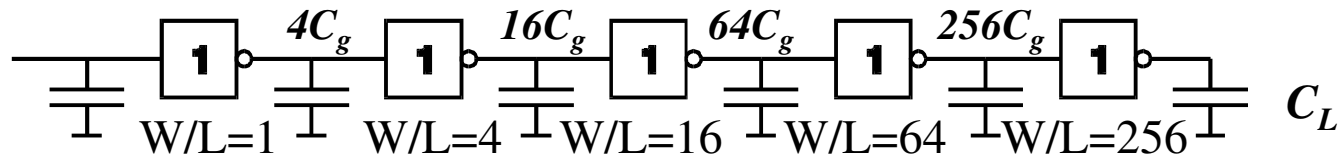


Five stage driver chain for $C_L / C_g = 1024$

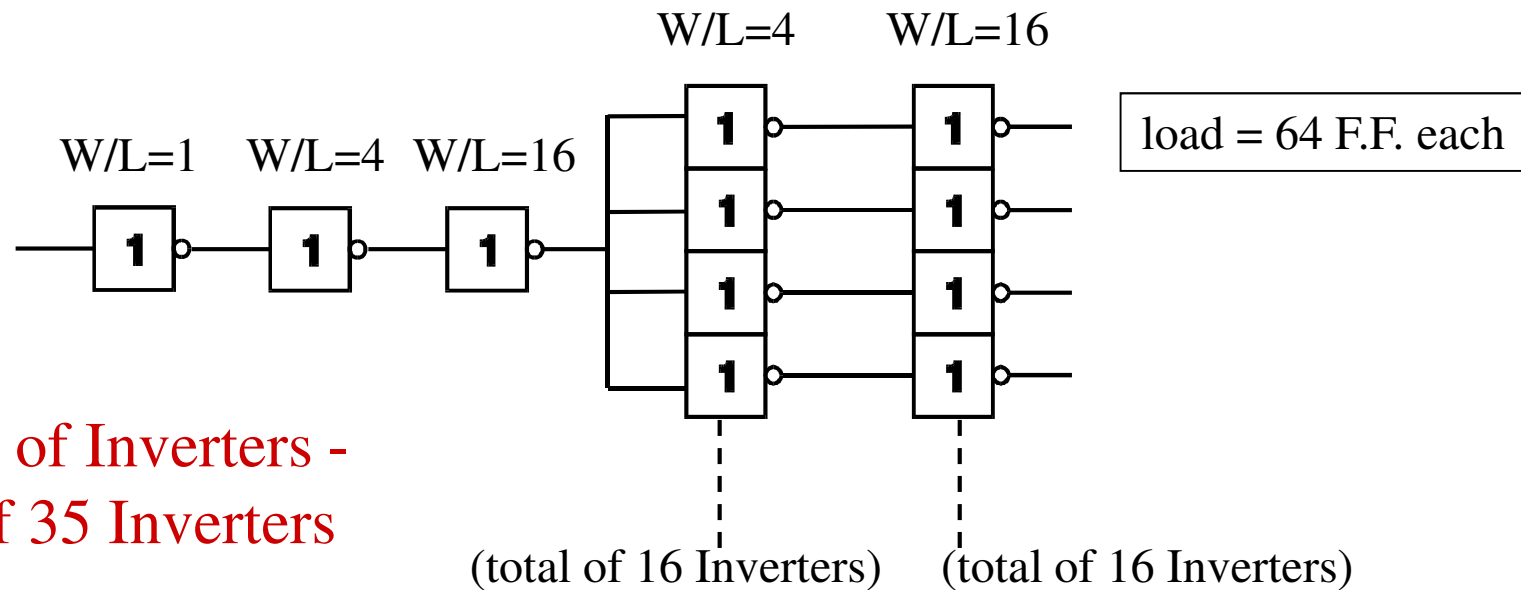


2 Types of Inverters –
total of 86 Inverters

Driver arrangement for clock sub-network (2)



Five stages driver chain for $C_L / C_g = 1024$



3 Types of Inverters -
total of 35 Inverters

Clock Design

Compromise between

- Robustness and complexity
- Constraints of Logics versus Constraints of Clock

Clock Method:

- Pulse control
- Edge control
- Single-phase Clock
- Two-phase Clock

Comparison Clock-Method

Pulse mode

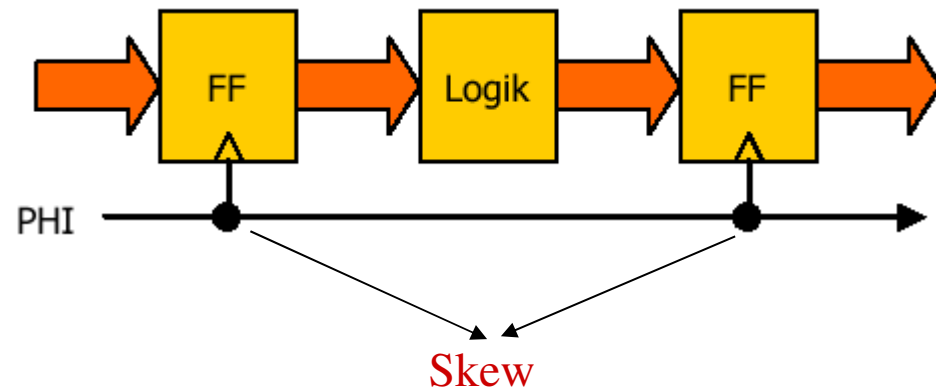
+ simple

- Signal delay time should not be too big or too small
- Pulse width critical (50%)

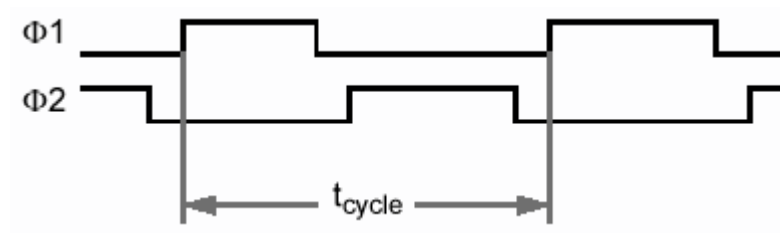
Edge control

+ more robust than pulse mode

- Skew of Clock signals on each FF/Registers can be a problem



Solution: two-phase Clock



11. Sequential Circuits

1. Realization of Registers (Latches, Flip-Flops)

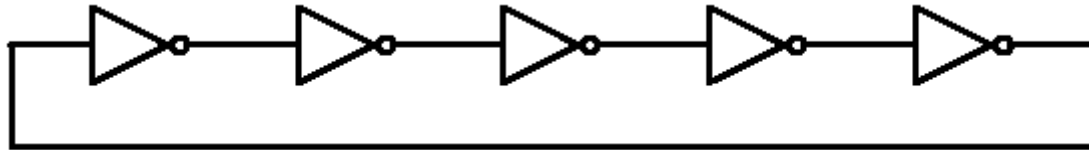
1. Dynamic Registers
2. Static Registers

2. Pipeline

3. Clock Distribution – Clock Networks

4. Clock Generation

Principle of Ring Oscillator



Inverter chain with feedback

Odd number of inverters in the loop

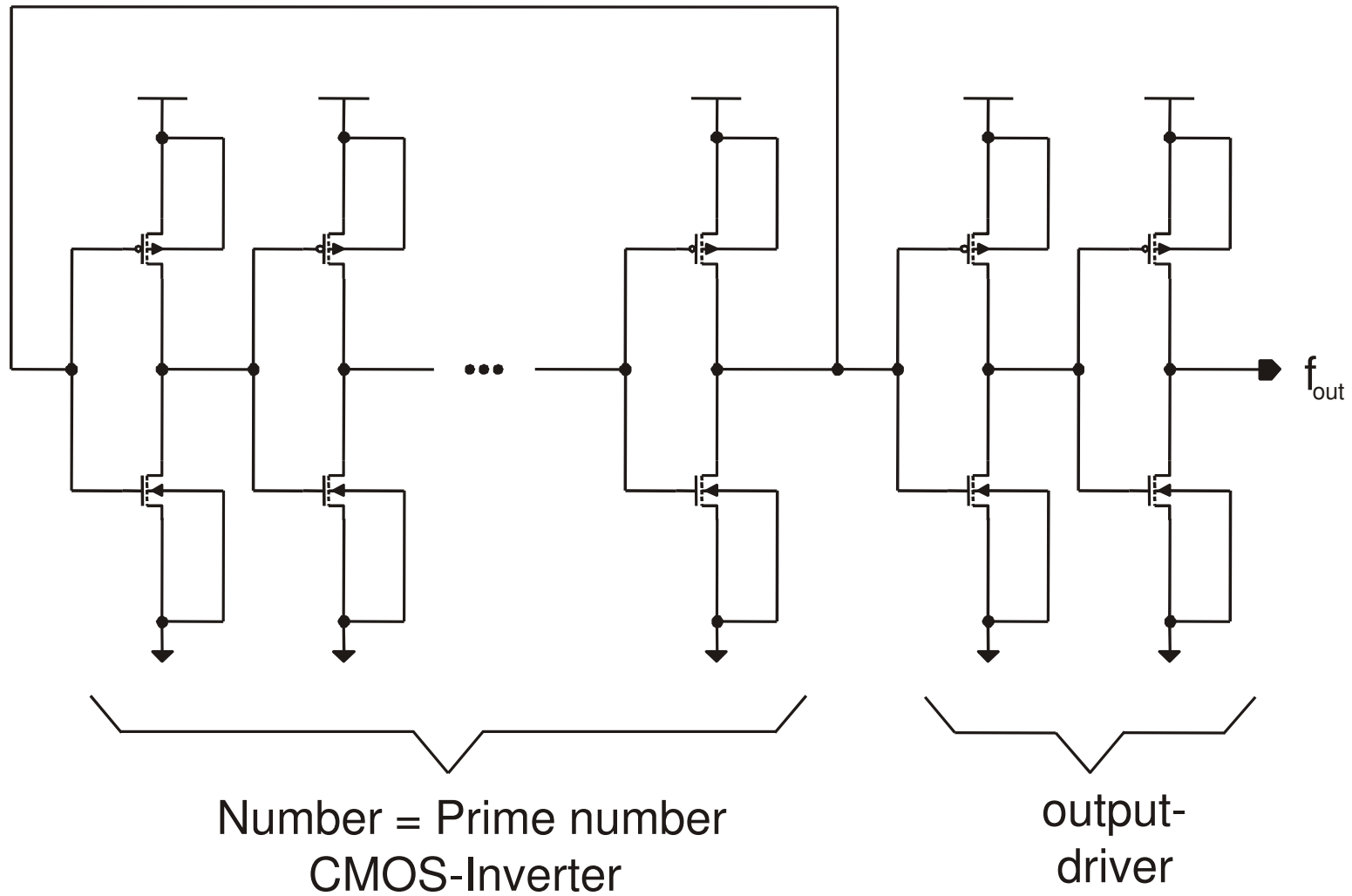
How would it be with an even number?

Latch

Periode of the oscillator ? $n \times \text{delay time of inverter}$

The number of inverters has to be a prime number.

Ring oscillator circuit



Realization for clock generation

1) Ring oscillator

+ pure integrated solution

- Subject to frequency, temperature and process variations

Ring oscillator is used in PCM

2) RC-Oscillator

External components are necessary (R, C resp. Resonator),
Frequency accuracy in percentage range

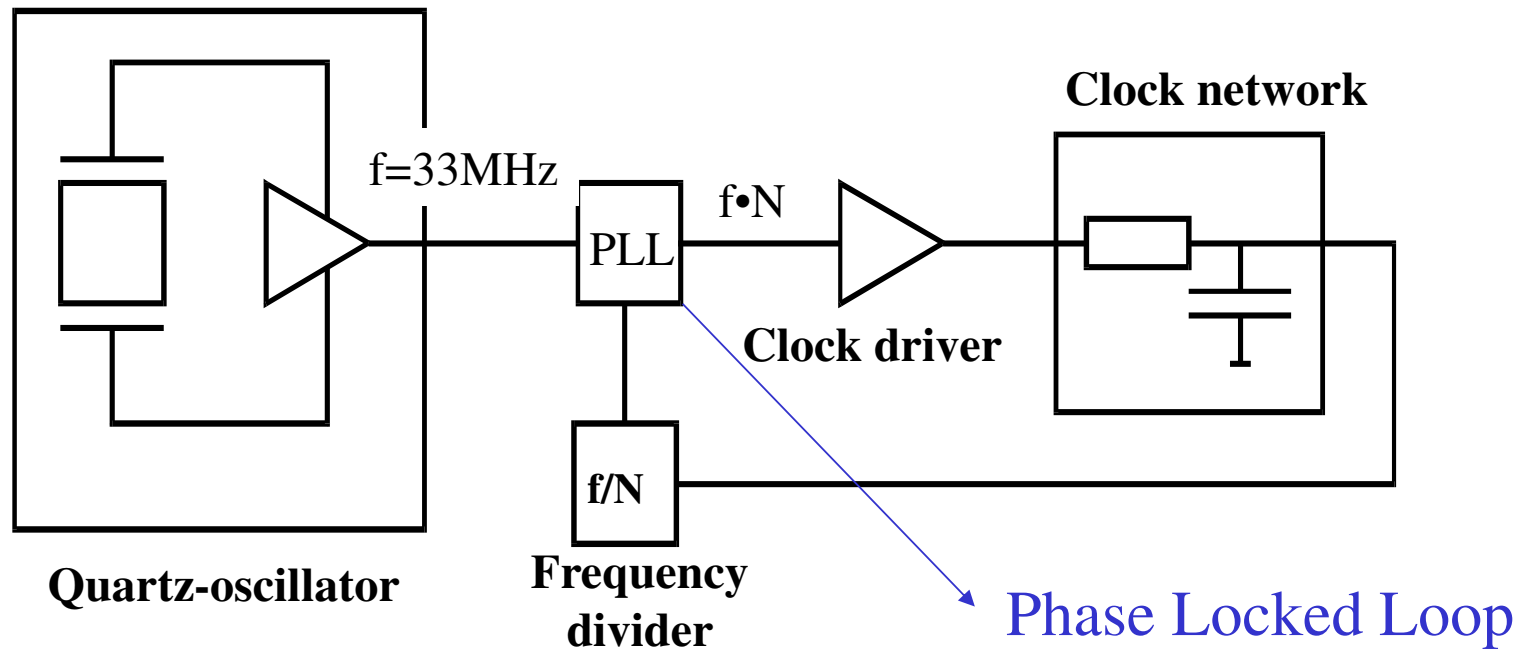
3) Crystal/Quartz

+ extremely accurate frequency

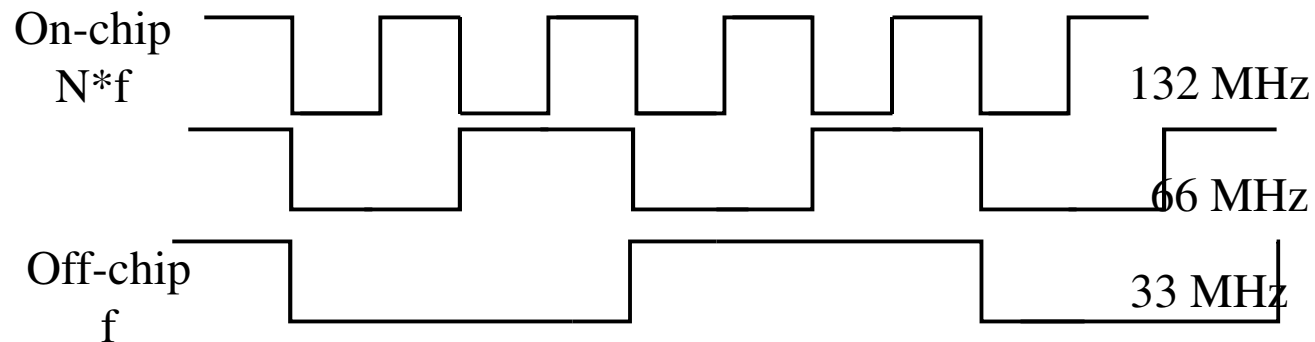
- expensive

Frequency of resonator and quartz is in MHz-range

Clock reproduction



Generation of clock signal



Composition of a Chip

12. Periphery of a chip

- 1. Input-Pads**
- 2. Output-Pads**
- 3. Tri-State-Driver**

13. Arrangement of components on a chip

Requirements on in- and outputs

ESD-protection

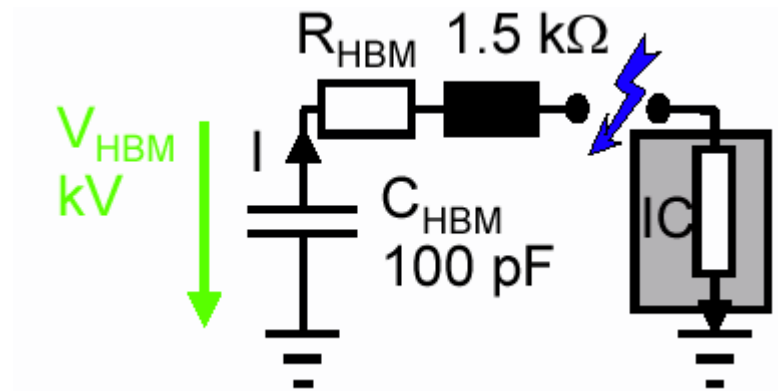
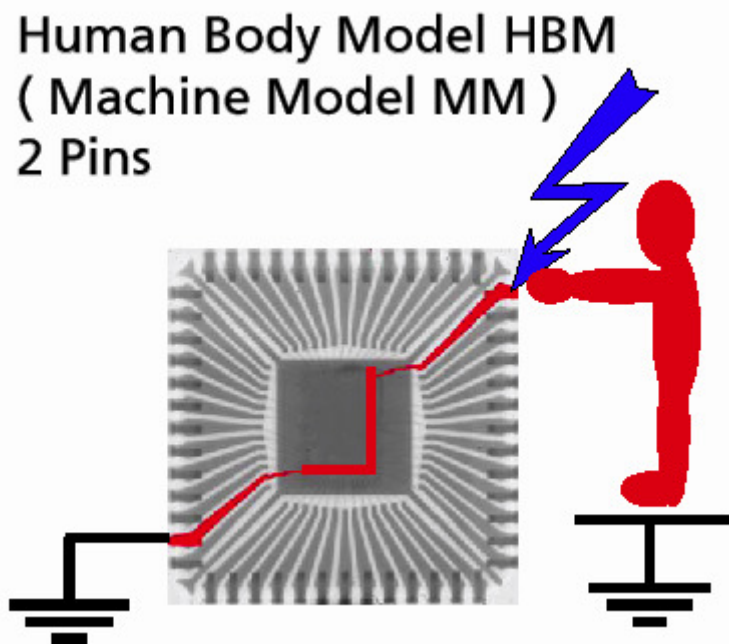
Mixed in- and output

Level shifter

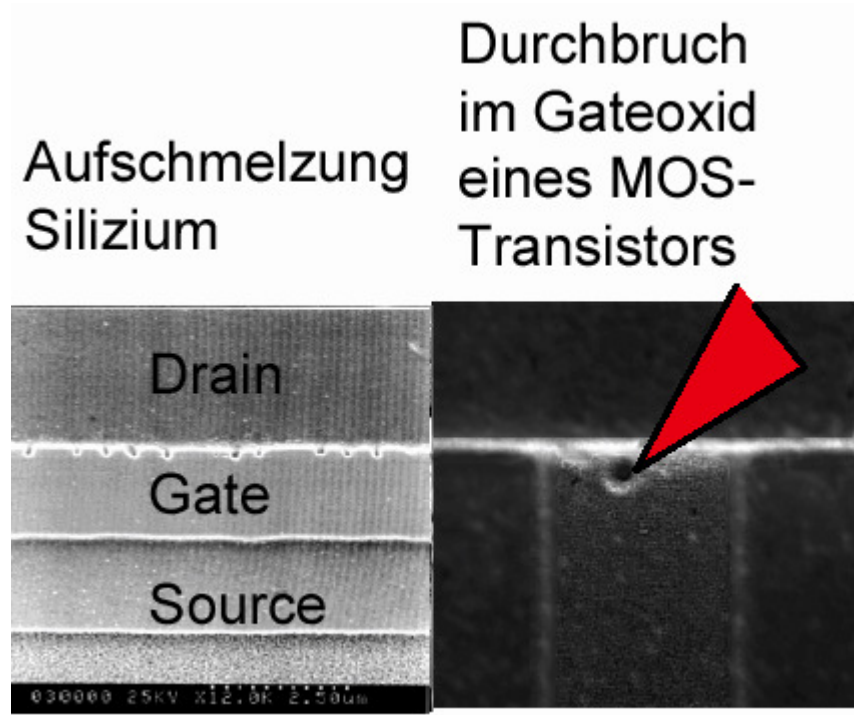
Analog-Digital converter (input)
and Digital-Analog-converter (output)

Tristate, Common drain output

ESD Stress Model



Effects: Damages in integrated circuits



Destruction of the thin Gate

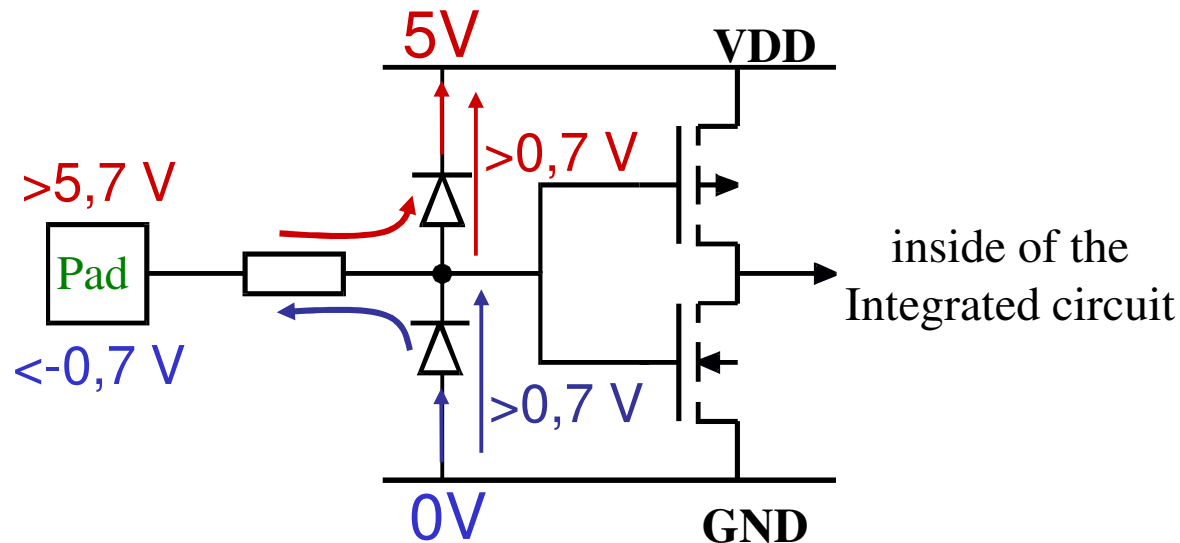


Equal to Phenomenon
lightning



Solution

ESD-Protective Circuit



Input-Pad with protective circuit

ESD-voltage (e.g. 2 kV) and energy is dissipated in ESD-resistor (1,5 k Ω) and the Pad-resistor.

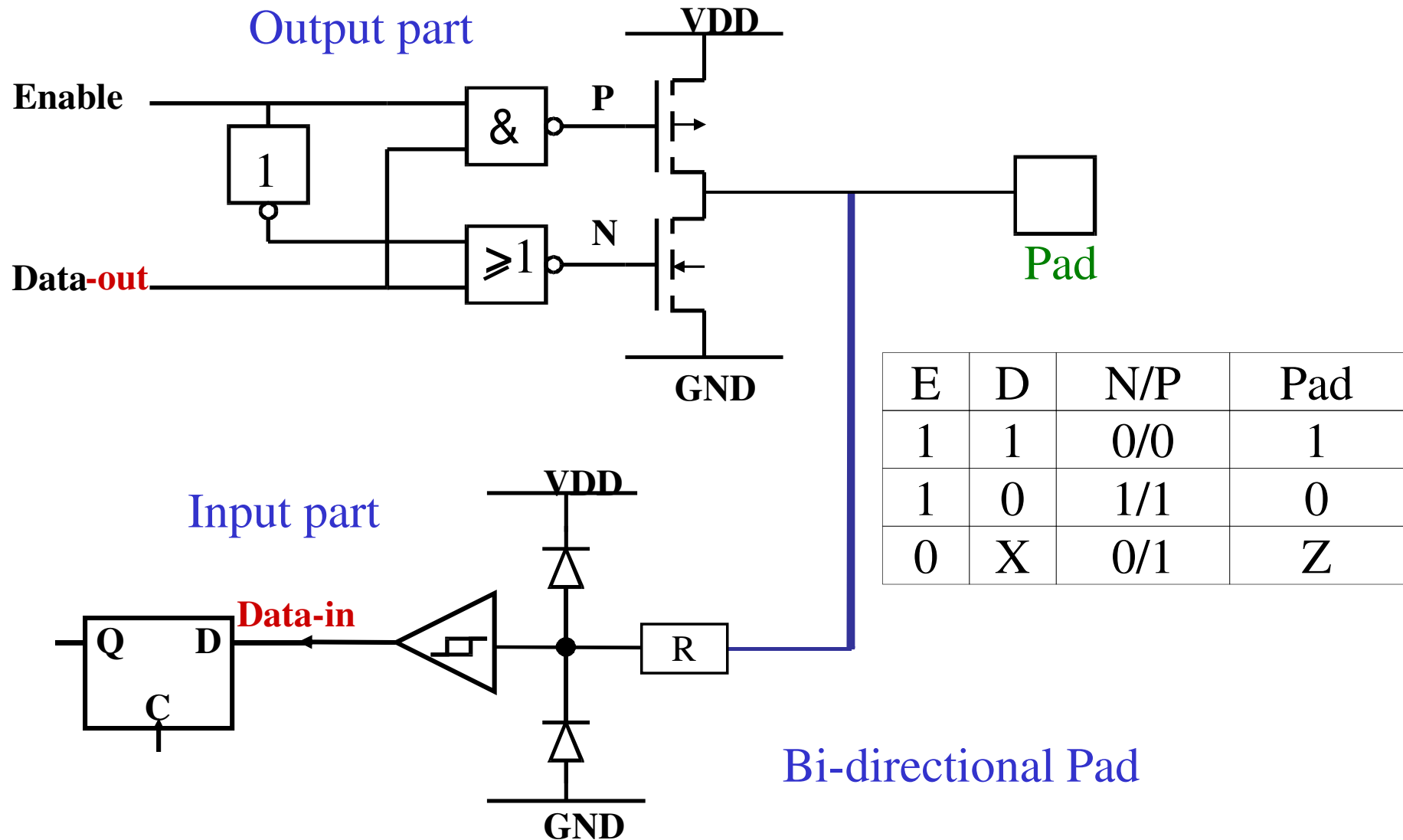
The gates at the input must not receive high voltage.

Modern ESD-protection circuits use transistors instead of diode.

For digital circuits **ESD-protection** including layout is included **in Pad-Library**.

For **special analog pads** (HF, HV etc.) **a proprietary design** is needed.

Mixed In- and Output + Tri-State-Pad

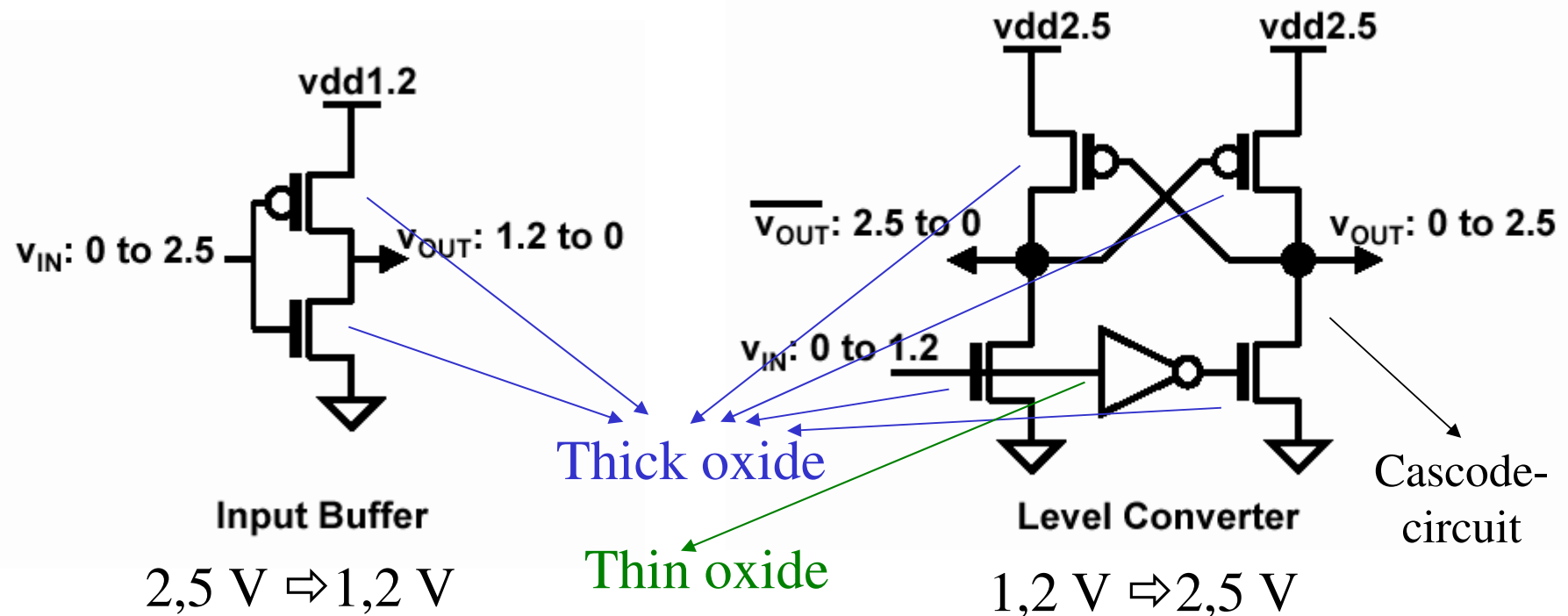


Level Shifter

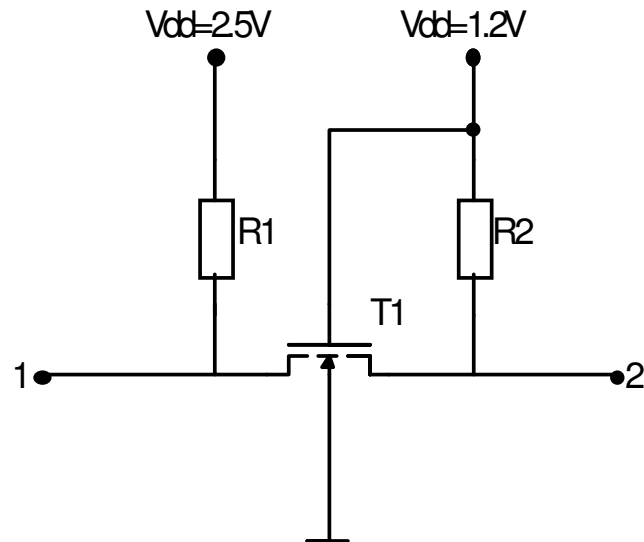
A modern IC process has always two gateoxides with two voltage classes (e.g. 1,2 V / 2,5 V)

In- and outputs are operated with higher voltage, whereas the inner logic-core receives only low voltage.

A conversion between these voltages is therefore necessary.



Level converter for mixed in-and outputs

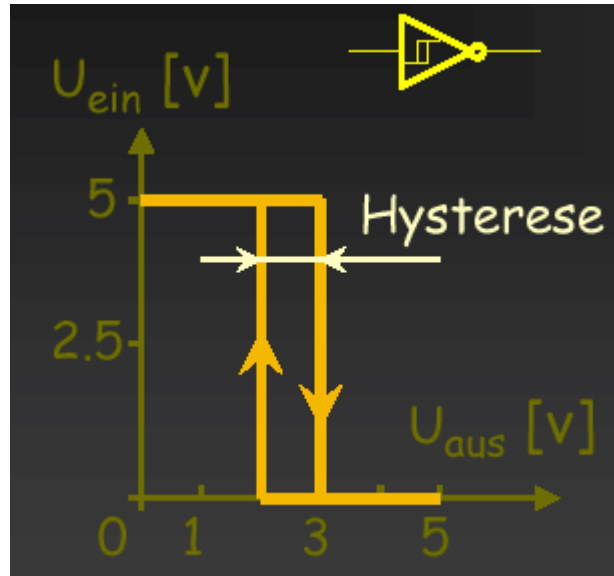


Common Gate Circuit

Input	node 1	0	2.5
Output	node 2	0	1.2
T1		on	off
I(T1)		$1.2/R2$	0
i(input)		$2.5/R1 + 1.2/R2$	0

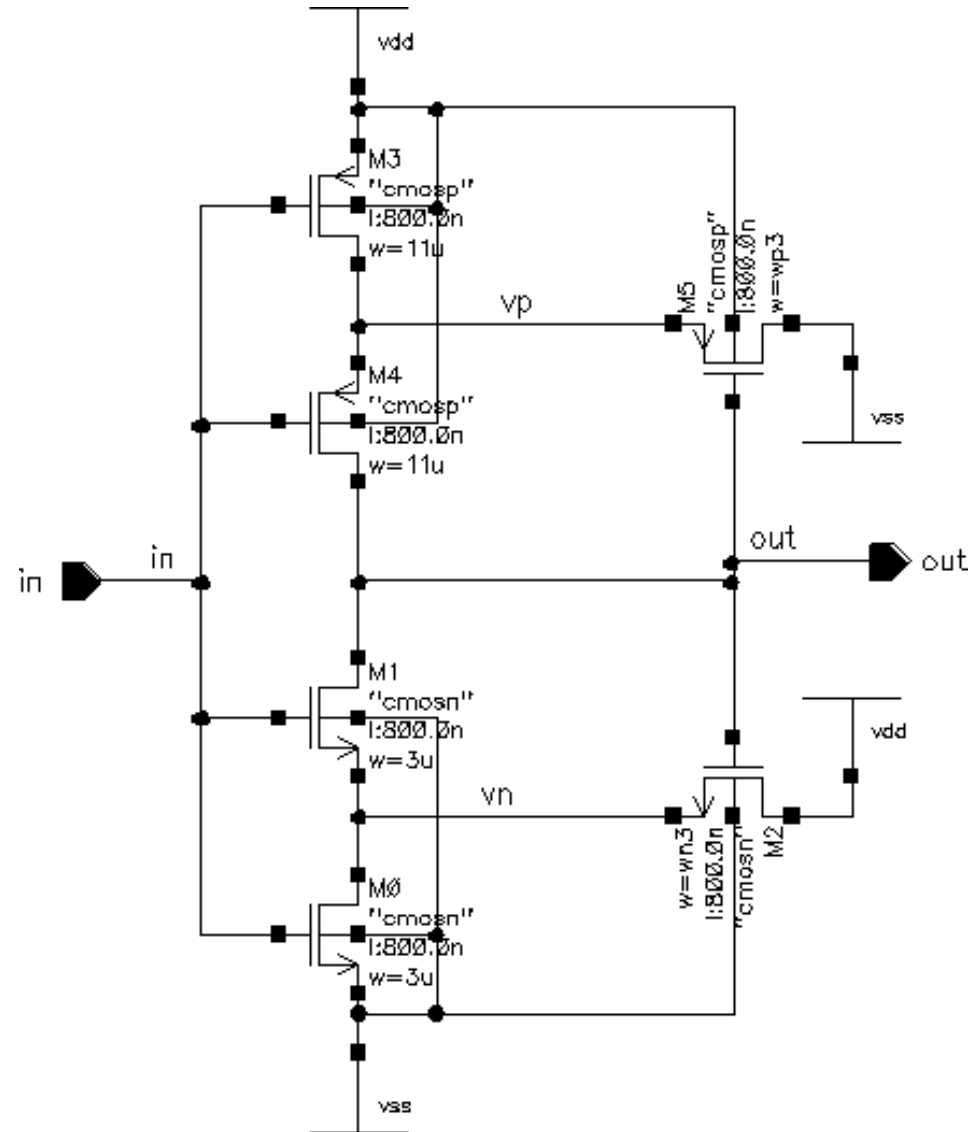
Input	node 2	0	1.2
Output	node 1	0	2.5
T1		on	off
I(T1)		$2.5/R1$	0
i(input)		$2.5/R1 + 1.2/R2$	0

Schmitt-Trigger



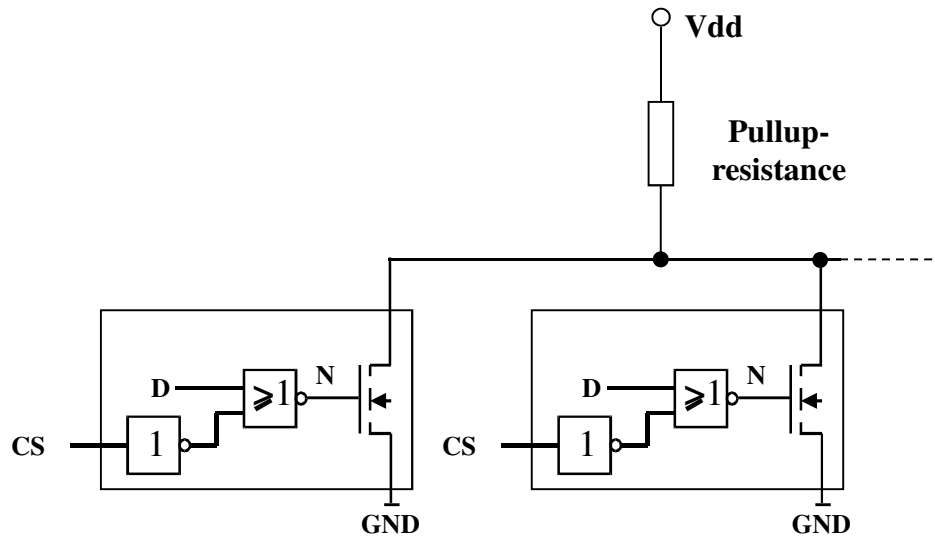
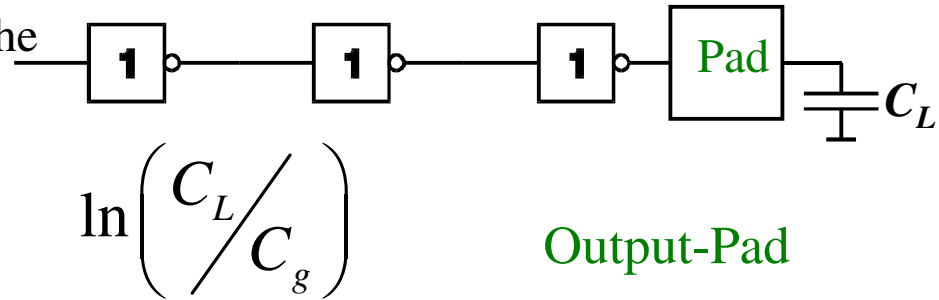
Hysteresis suppresses noise/
disturbances at input and
prevents Oscillation at output

„1 Bit Analog-Digital-converter“

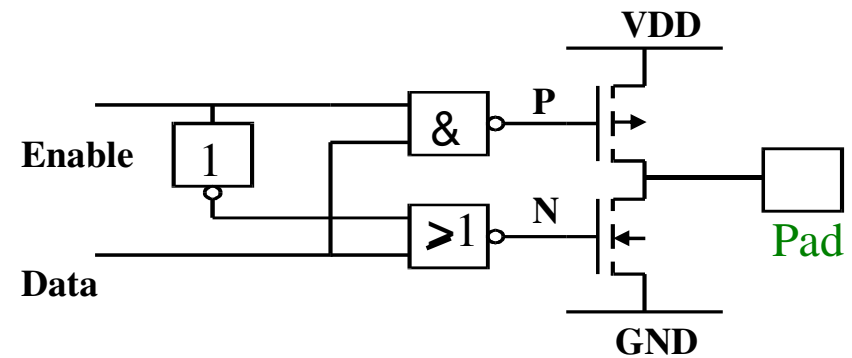


Output driver-I/O-Driver

From the inside of the
Circuit



Open Drain Output



Tristate Pad

Arrangement of Pads, Logics, Clock- and Supply lines on a Chip

